Preliminary Amendment

Filed: June 9, 2006

## IN THE CLAIMS:

Claims 1 through 19 (Cancelled)

20. (New) A method for creating a light assembly including a light-emitting diode and a printed circuit board having conductors printed thereon, the method comprising the steps of:

positioning the light-emitting diode on the printed circuit board;
connecting the light-emitting diode to the printed circuit board;
positioning the light-emitted diode and the printed circuit board in a mold; and
injecting a thermoplast into the mold such that the thermoplast extends on both sides of
the printed circuit board and over the light-emitting diode.

- 21. (New) A method as set forth in claim 20 wherein the step of injecting the thermoplast includes forcing the thermoplast through a hole in the printed circuit board.
- 22. (New) A method as set forth in claim 21 including the step of orienting the lightemitted diode below the printed circuit board before positioning the printed circuit board in the mold.
- 23. (New) A method as set forth in claim 22 wherein the step of positioning the light-emitting diode includes the step of aligning the light-emitted diode with respect to the conductors on the printed circuit board.
- 24. (New) A method as set forth in claim 23 wherein the step of aligning includes the step of aligning the light-emitted diode with an edge of the hole.
- 25. (New) A method as set forth in claim 24 including the step of forming an optical lens with the thermoplast.
- 26. (New) A method as set forth in claim 25 including the step of electrically connecting the light-emitting diode to the printed circuit board with a bond wire.
- 27. (New) A method as set forth in claim 26 including the step of encasing the bond wire in the thermoplast.
- 28. (New) A method as set forth in claim 24 wherein the thermoplast forms a light distributing element on the side of the printed circuit board to which the light-emitting diode is connected.

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29. (New) A method as set forth in claim 28 including the step of forming a fastening section of the thermoplast on a side of the printed circuit board opposite the side to which the light-emitted diode is connected.